# DA2J108

Silicon epitaxial planar type

### For small current recitification

### Features

- Small reverse current I<sub>R</sub>
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub>	300	V	
Maximum peak reverse voltage	V <sub>RM</sub>	300	V	
Output current (Average)	I <sub>O(AV)</sub>	200	mA	
Repetitive peak forward current	I <sub>FRM</sub>	600	mA	
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	А	
Junction temperature	Tj	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

Note) \*: 1 t = 1 s

### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage (DC)	V <sub>F</sub>	$I_F = 200 \text{ mA}$			1.2	V
Reverse current (DC)	I <sub>R1</sub>	$V_R = 200 V$			200	nA
	I <sub>R2</sub>	$V_{R} = 300 V$			1	μΑ
Terminal capacitance	Ct	$V_{R} = 0 V, f = 1 MHz$		3.5		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

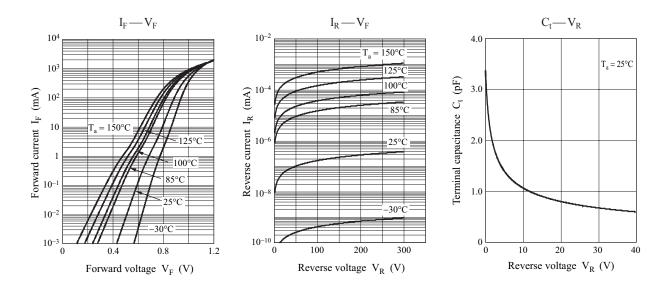
2. Absolute frequency of input and output is 3 MHz

## Package

- Code
- SMini2-F5-B
- Pin Name
- 1: Cathode
- 2: Anode
- Marking Symbol: A2

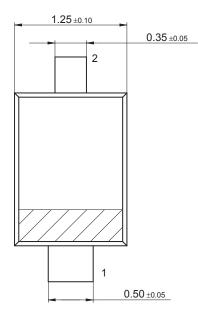
# DA2J108

# **Panasonic**



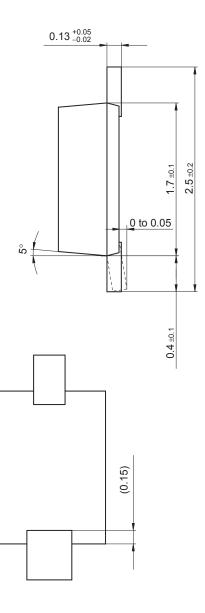
# SMini2-F5-B

Unit: mm



 $0.7 \pm 0.1$ 

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